

MAP 2014

The 14th International Workshop on Microelectronics Assembling and Packaging

MAP2014 Program Overview

20 th October, 2014	
10:30 ~ 10:35	Opening Remark
10:35 ~ 12:10	Session 1: Invited Talk The 10 th anniversary Memorial Session of Non-Profit Organization Semiconductor Technologies Marketing (STM)
12:10 ~ 13:10	Lunch Break
13:10 ~ 14:40	Session 2: Advanced Design and Test Technology
14:40 ~ 15:10	Break
15:10 ~ 16:50	Session 3: Device Embedding Technology
16:50 ~ 17:10	Break
17:10 ~ 17:50	Session 4: Semiconductor Business in Southeast Asia
18:00 ~ 19:15	Poster Session & Reception Party @BIZCOLI

MAP2014 Program

Monday 20th, October

10:30~10:35 Opening Remark

Hajime Tomokage
Fukuoka University (JAPAN)

10:35~12:10 Session 1: Invited Talks

*The 10th anniversary Memorial Session of Non-Profit Organization Semiconductor Technologies Marketing (STM)

Chair: Wei-Chung Lo
Industrial Technology Research Institute (TAIWAN)

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|-------------|-----|--|
| 10:35-11:30 | 1-1 | Future of Semiconductor Industry
Yukio Sakamoto
<i>Win Consultant (JAPAN)</i> |
| 11:30-12:10 | 1-2 | Samsung's Prosperity and Shadow "Retain the Sustainable Growth in the future?"
Masaaki Nomi
<i>Former TOSHIBA Device Corporation (JAPAN)</i> |

12:10 ~ 13:10 Lunch Break

13:10~14:40 Session 2: Advanced Design and Test Technology

Chair: Yoshihisa Katoh
Fukuoka University (JAPAN)

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| 13:10-13:40 | 2-1 | Nanotechnology in Electronics Packaging, Interconnect, & Assembly: Hype or Reality?
Charles E. Bauer
<i>Tech Lead Corporation (U.S.A.)</i> |
| 13:40-14:00 | 2-2 | New Test Equipment for Next Generation RF Application
Eiji Mori
<i>SONIX Corporation (JAPAN)</i> |
| 14:00-14:20 | 2-3 | Electrical Test Method for Printed Circuit Board with Embedded Components
Munehiro Yamashita
<i>NIDEC-READ Corporation (JAPAN)</i> |
| 14:20-14:40 | 2-4 | Through Silicon Via Process Using DRIE and Cathode PE-CVD
Fumiharu Matsuo
<i>SAMCO Inc. (JAPAN)</i> |

14:40 ~ 15:10 Break

15:10~16:50 Session 3: Device Embedding Technology

Chair: Hajime Tomokage

Fukuoka University (JAPAN)

- 15:10-15:30 3-1 Device Embedded Technology: Present and Future
Wei-Chung Lo
Industrial Technology Research Institute (Taiwan)
- 15:30-15:50 3-2 DES & International Standardization - JPCA perspective -
Kunio Takahara
Japan Electronics Packaging and Circuits Association (JAPAN)
- 15:50-16:10 3-3 SoC/SiP/PCB Co-Design solutions by CR-8000 Design Force
Kazunari Koga
Zuken Inc. (JAPAN)
- 16:10-16:30 3-4 Standardization of Electrical Test for Device Embedded Substrate
Hyunho Kim
Center for Integrated Smart Sensors (KOREA)
- 16:30-16:50 3-5 Cu-Cu Direct Bonding Technology for 2.5D/3D Integration
Taiji Sakai
Fujitsu Laboratories Ltd. (JAPAN)

16:50~17:10	Break
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17:10~17:50 Session 4: Semiconductor Business in Southeast Asia

Chair: Ema Hirata

Kyushu Economic Research Center (JAPAN)

- 17:10-17:30 4-1 The IC Industry of Vietnam – Present & Future –
Dang Luong Mo
Integrated Circuit Design and Education, Vietnam National University Ho Chi Minh(VIETNAM)
- 17:30-17:50 4-2 Trends of India Semiconductor Industry
Dorai Arasu
InfoSree Technologies Pvt., Ltd. (INDIA)

18:00~19:15 Poster Session & Reception Party

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|------|----------------------------------|------|--|
| 5-1 | Hibikino System-Lab Inc. | 5-2 | FUKUDEN SHIZAI K.K. |
| 5-3 | Hitachi Maxell, Ltd. | 5-4 | Zuken Inc. |
| 5-5 | ELIA Co., Ltd. | 5-6 | Noda Screen Co., Ltd. |
| 5-7 | WALTS Co., Ltd. | 5-8 | SAMCO Inc. |
| 5-9 | Kamiens Technology Inc. | 5-10 | Industrial Technology Research Institute |
| 5-11 | Infosree Technologies Pvt., Ltd. | 5-12 | Sato-Shoji(Hong Kong Co., Ltd.) |
| 5-13 | NIDEC-READ Corporation | 5-14 | Frontier Semiconductor, Inc |

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御申込書

MAP2014 セミナー	<input type="checkbox"/> 参加する	<input type="checkbox"/> 参加しない
レセプションパーティー	<input type="checkbox"/> 参加する	<input type="checkbox"/> 参加しない

御申込者

氏名

氏名(英語表記)

※パスを作成いたしますので、必ずご記入ください。

会社名

部署・役職

住所 〒

E-mail

電話

Fax

申込方法

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- 参加費用は、15,000 円です。参加費用の中には、配布資料、レセプションパーティーの料金を含みます。
 - 御申込用紙に必要事項を記入の上、アジア半導体機構事務局（担当：中川、居石）、FAX(092-721-4904)もしくは E-mail(astsa@kerc.or.jp)までお送り下さい。
 - 折り返し、ご請求書をお送りします。

下記までお送り下さい。

アジア半導体機構 (ASTSA) 担当：居石、中川

Fax の方 → 092-721-4904

E-mail の方 → astsa@kerc.or.jp

---開催場所---

MAP2014

会期:20年10月20日(月) 10:30~19:00

会場:電気ビル共創館 3F

福岡市中央区渡辺通 2-1-82

最寄り駅:福岡市営地下鉄 渡辺通駅 直結

西鉄薬院駅 徒歩5分



Google Map

---お問い合わせ先---

MAP2014

MAP2014 実行委員会事務局(公益財団法人九州経済調査協会内)

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